



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

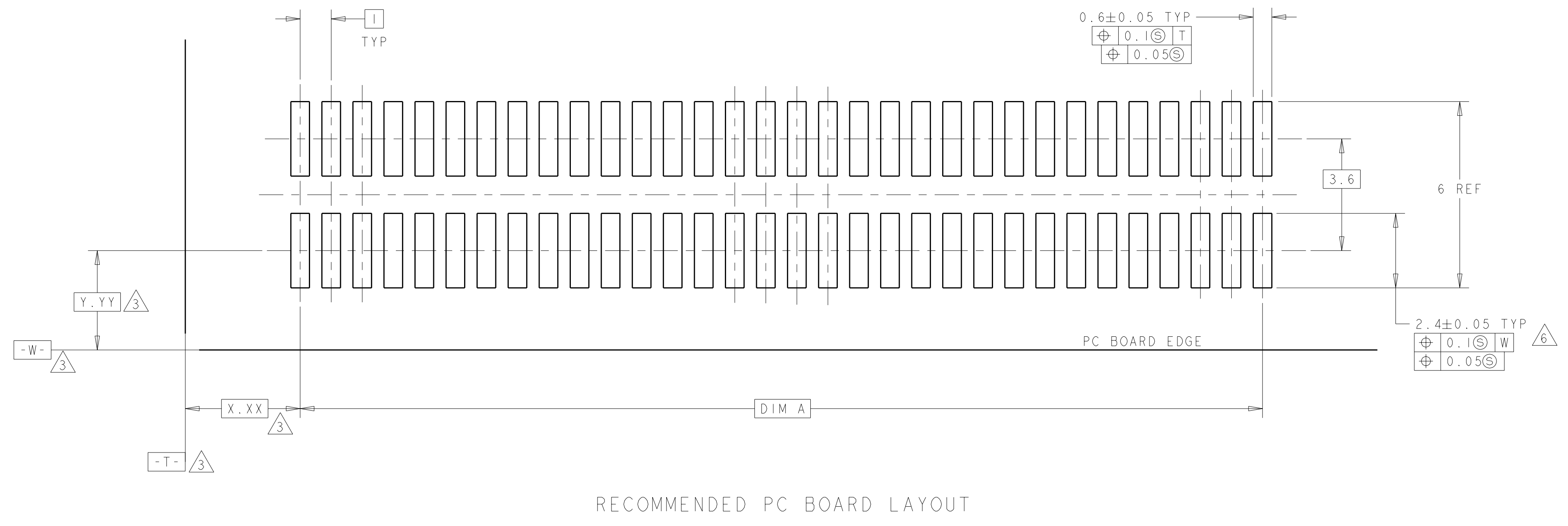
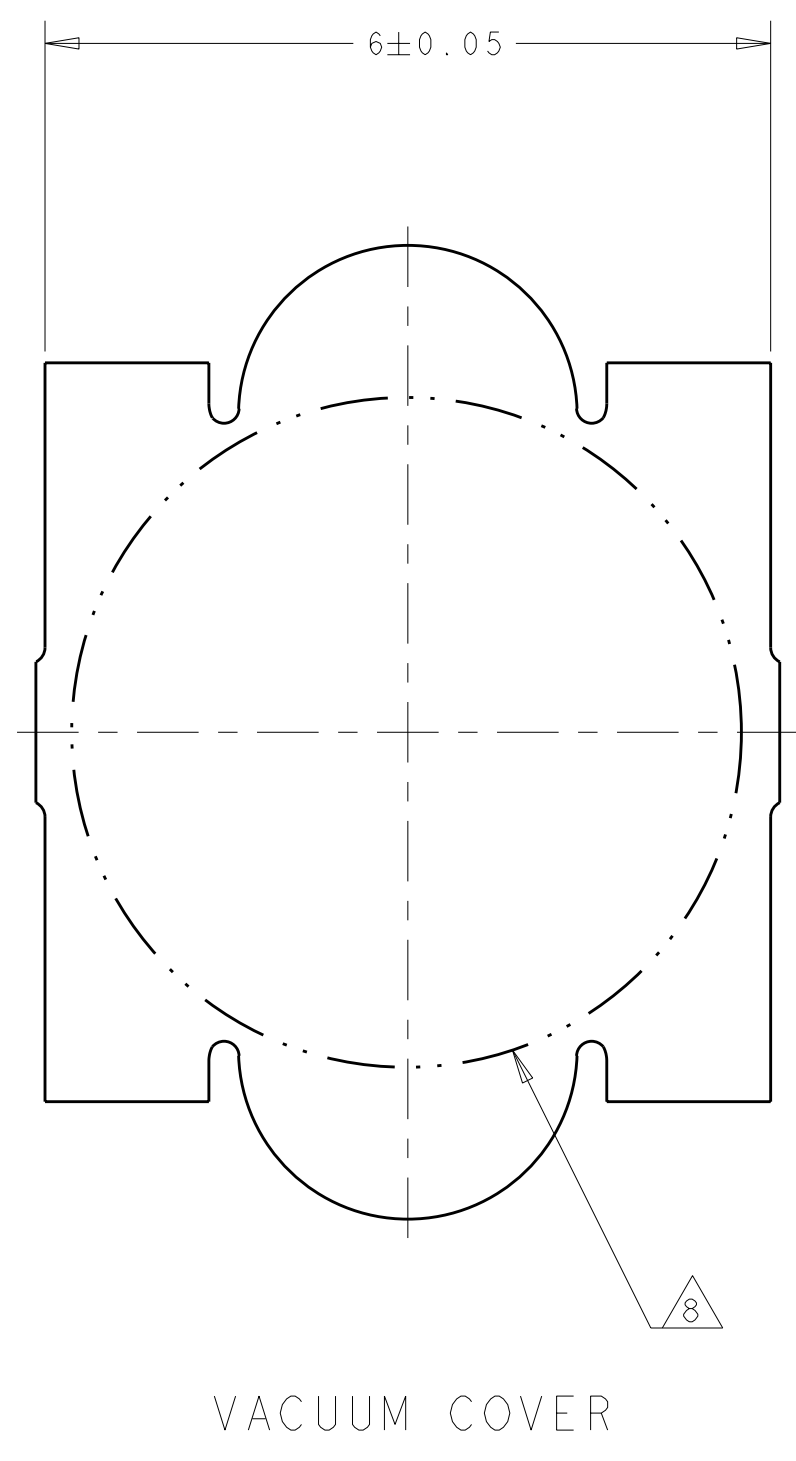
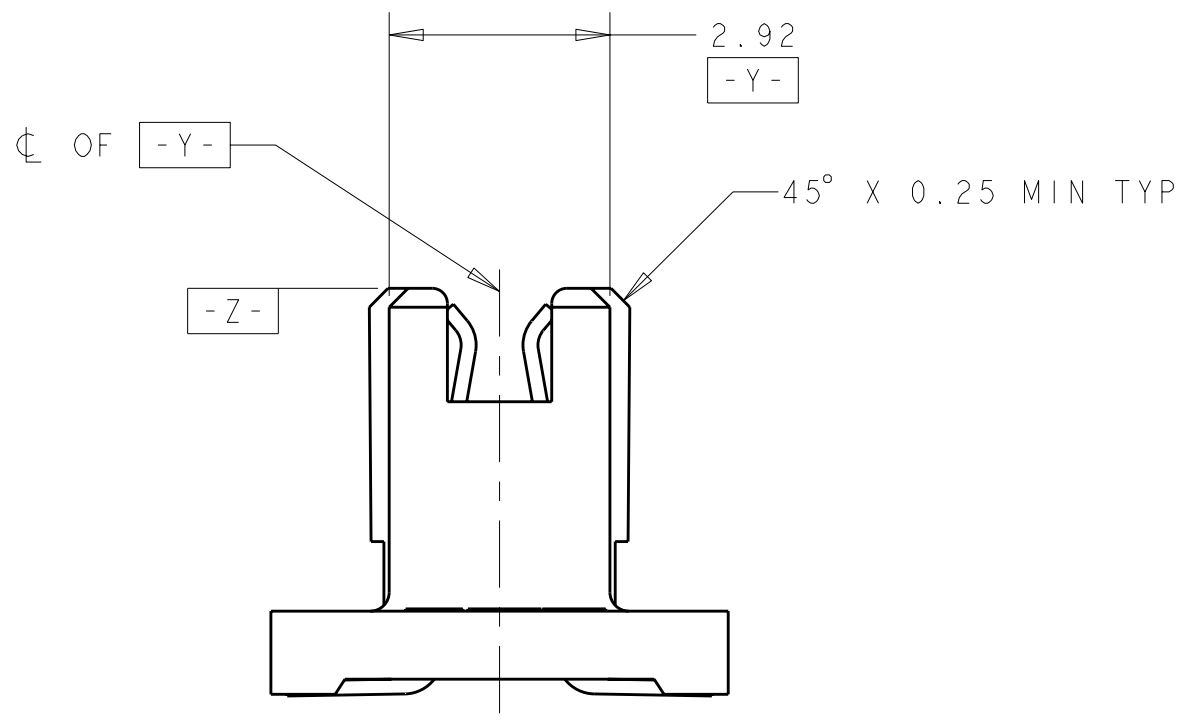
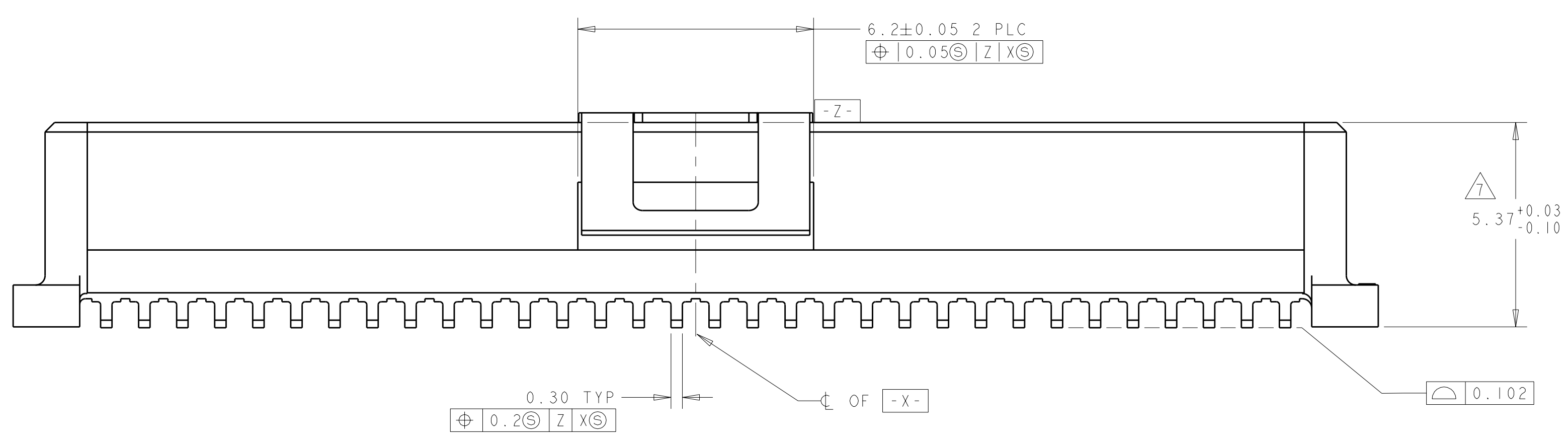
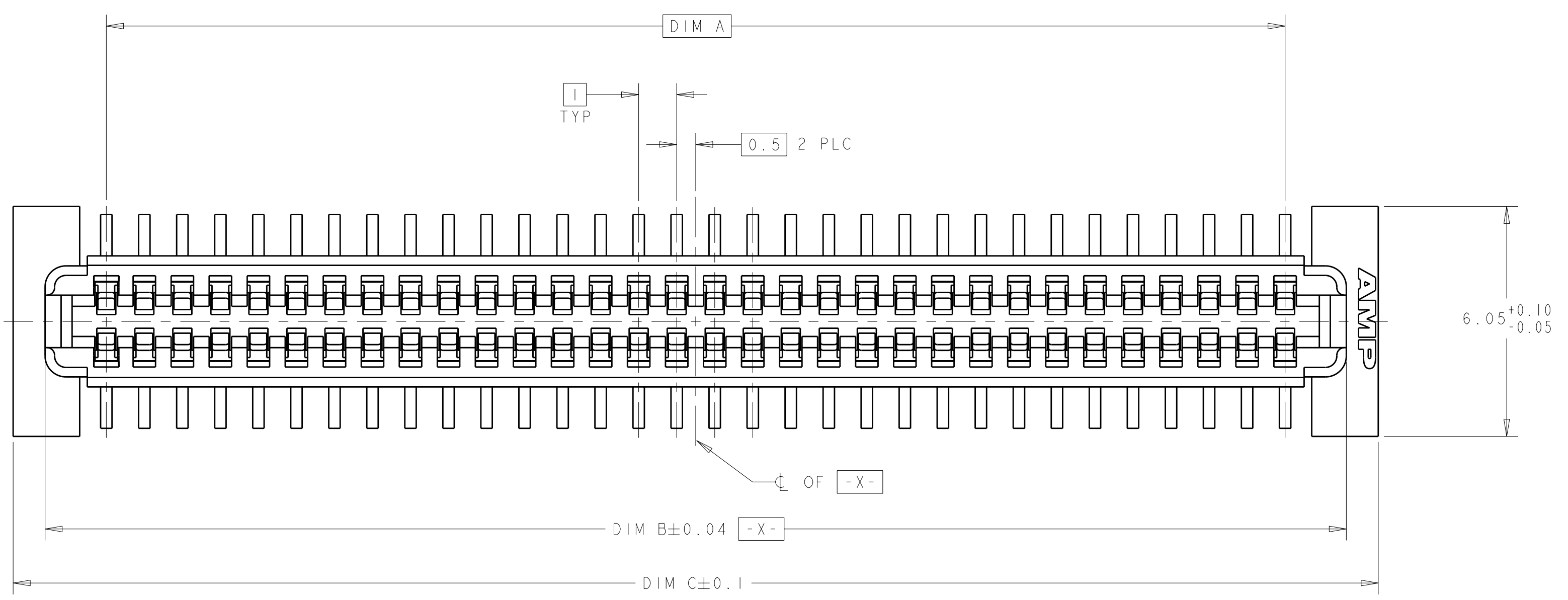
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LOC	DIST	REV	DATE	BY	CHKD	APVD
AD	00	A1	18MAR2011	RK	HMR	



RECOMMENDED PC BOARD LAYOUT

- 1 HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR: BLACK
CONTACT MATERIAL: PHOSPHOR BRONZE
- 2 CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES
PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY
SPECIFICATION EIA-700AAAAB, SOLDER TAILS PLATED TIN.
- 3 DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE
CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE
CONNECTORS ON A PC BOARD.
- 4. PACKAGED IN TAPE ON REEL PER EIA-481.
- 5. VACUUM COVER DESIGNED FOR 4mm DIA. NOZZLE. COVER TO BE REMOVED
AFTER SOLDERING. COVER OMITTED FROM SOME VIEWS FOR DIMENSIONAL
CLARITY.
- 6 SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAAB, HOWEVER 2.4
LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF
MANUFACTURER OF CONNECTOR.
- 7 REFERRED TO AS DIM H = 5.30 ± 0.1 IN EIA 700AAAAB SPECIFICATION.
- 8 5.5 MIN DIA TARGET AREA FOR VACUUM PICK-UP.
- 9 CONTACT FINISH: 0.00381 MINIMUM MATTE TIN PER ASTM B 545
ON SOLDER AREA, 0.00127 MINIMUM GOLD PER ASTM B 488 ON MATING AREA,
BOTH OVER 0.00127 MINIMUM NICKEL PER SAE-AMS-QQ-N-290 ON ENTIRE CONTACT.

FINISH	DIM C	DIM B	DIM A	MATING CONNECTOR	STACK HGTS	POS	PART NO
9	45.9	44.22	41	120534-2	10	84	1-5120528-2
9	45.9	44.22	41	120533-2	9	84	1-5120528-2
9	45.9	44.22	41	120532-2	8	84	1-5120528-2
9	35.9	34.22	31	120534-1	10	64	1-5120528-1
9	35.9	34.22	31	120533-1	9	64	1-5120528-1
9	35.9	34.22	31	120532-1	8	64	1-5120528-1
2	45.9	44.22	41	120534-2	10	84	5120528-2
2	45.9	44.22	41	120533-2	9	84	5120528-2
2	45.9	44.22	41	120532-2	8	84	5120528-2
2	35.9	34.22	31	120534-1	10	64	5120528-1
2	35.9	34.22	31	120533-1	9	64	5120528-1
2	35.9	34.22	31	120532-1	8	64	5120528-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DWG: B. CARBO 27SEP04
 CHK: R. WERTZ 27SEP04
 APVD: R. WERTZ 27SEP04

TE Connectivity

RCPT ASSY, W/COVER, 1.0mmFH (IEEE1386) CONNECTOR

114-25045
 WEIGHT: -
 SCALE: 10:1

100779C=5120528